

# MA2J114 (MA114)

## Silicon epitaxial planar type

For small power rectification

### ■ Features

- S-mini type package, allowing high-density mounting
- High reverse voltage  $V_R$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	150	V
Maximum peak reverse voltage	$V_{RM}$	150	V
Output current	$I_O$	200	mA
Repetitive peak forward current	$I_{FRM}$	600	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	1	A
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

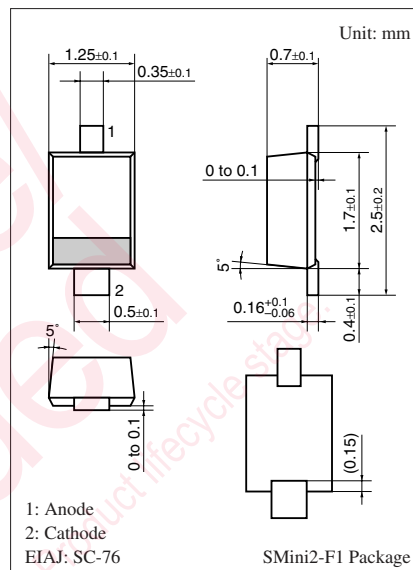
Note) \*:  $t = 1\text{ s}$

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 200\text{ mA}$			1.2	V
Reverse current	$I_R$	$V_R = 150\text{ V}$			200	nA
Terminal capacitance	$C_t$	$V_R = 0\text{ V}, f = 1\text{ MHz}$		4.5		pF

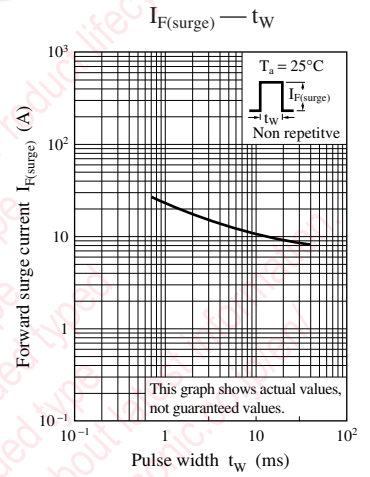
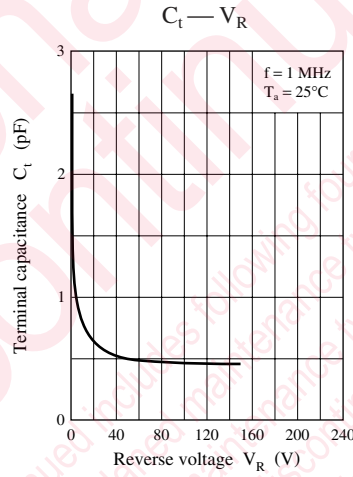
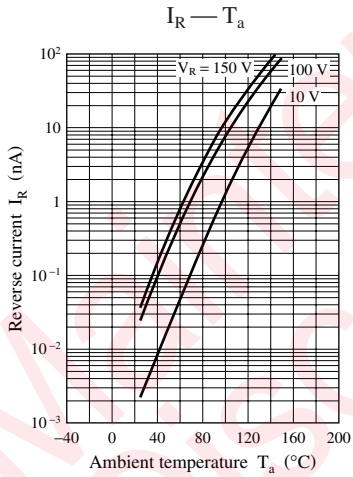
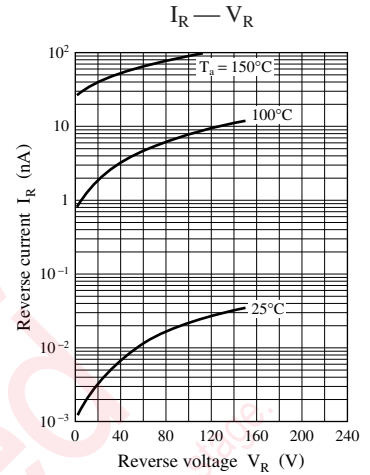
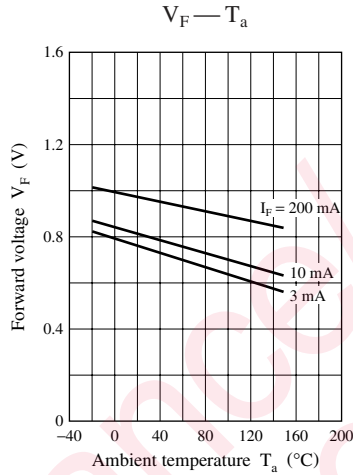
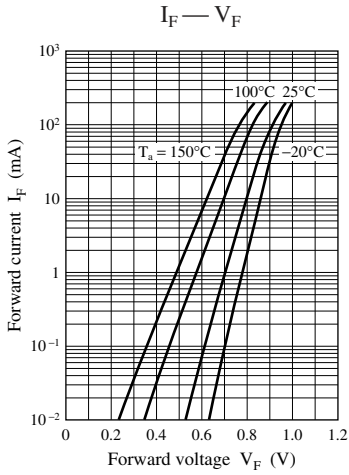
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 3 MHz.



Marking Symbol: 1E

Note) The part number in the parenthesis shows conventional part number.



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